ON Semiconductor

Is Now

Onsemi

To learn more about onsemi[™], please visit our website at <u>www.onsemi.com</u>

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product factures, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and asfety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or by customer's technical experts. onsemi products and actal performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application, Buyer shall indemnify and hold onsemi and its officers, employees, subsidiari

Buffer with Open Drain Output

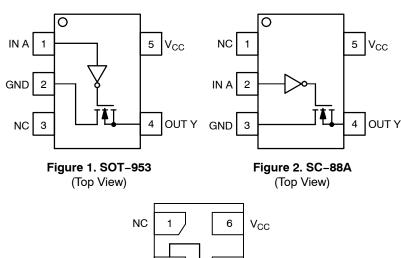
NL17SG07

The NL17SG07 MiniGate[™] is an advanced high-speed CMOS Buffer with Open Drain Output in ultra-small footprint.

The NL17SG07 input structures provides protection when voltages up to 5.5 V are applied with V_{CC} greater than or equal to 0.9 volts, otherwise the protection is up to 4.6 volts regardless of the supply voltage.

Features

- Wide Operating V_{CC} Range: 0.9 V to 3.6 V
- High Speed: t_{PD} = 2.5 ns (Typ) at V_{CC} = 3.0 V, C_L = 15 pF
- Low Power Dissipation: $I_{CC} = 0.5 \ \mu A \ (Max)$ at $T_A = 25^{\circ}C$
- 5.5 V Overvoltage Tolerant (OVT) Input Pins ($V_{CC} \ge 0.9 \text{ V}$)
- Ultra-Small Packages
- These are Pb-Free and Halide-Free Devices



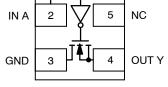






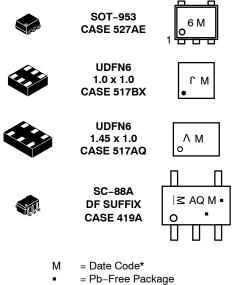
Figure 4. Logic Symbol



ON Semiconductor®

www.onsemi.com

MARKING DIAGRAMS



(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

PIN	SOT-953	SC-88A	UDFN6
1	IN A	NC	NC
2	GND	IN A	IN A
3	NC	GND	GND
4	OUT Y	OUT Y	OUT Y
5	V _{CC}	V _{CC}	NC
6	-	-	V _{CC}

FUNCTION TABLE

Input A	Output Y
L	L
Н	Z

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		–0.5 to +5.5	V
V _{IN}	DC Input Voltage	$\begin{array}{l} V_{CC} \geq 0.9 \ V \\ V_{CC} < 0.9 \ V \end{array}$	-0.5 to +5.5 -0.5 to +4.6	V
V _{OUT}	DC Output Voltage		–0.5 to V _{CC} + 0.5	V
Ι _{ΙΚ}	DC Input Diode Current	V _{IN} < GND	-20	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-20	mA
I _{OUT}	DC Output Source/Sink Current		±20	mA
I _{CC}	DC Supply Current per Supply Pin		±20	mA
I _{GND}	DC Ground Current per Ground Pin		±20	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		+150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3)	>2000 >100	V
I _{LATCHUP}	Latch-up Performance above V_{CC} and below GND at 12 $$	25°C (Note 4)	±75	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

Tested to EIA/JESD22–A114–A.
Tested to EIA/JESD22–A115–A.

4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	0.9	3.6	V
V _{IN}	Digital Input Voltage	0.0	3.6	V
V _{OUT}	Output Voltage Output at High or Low Tri–State Mode (N Power–Down Mode (V _{CC} :	ote 5) 0.0	V _{CC} 3.6 3.6	V
T _A	Operating Temperature Range	-55	+125	°C
Δt / ΔV	Input Transition Rise or Fail Rate V_{CC} = 3.3 V ±	0.3 V 0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability. 5. Applicable to devices with outputs that may be tri-stated.

DC ELECTRICAL CHARACTERISTICS

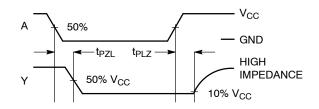
				Vcc		T _A = 25°C		–55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	с	ondition	(V)	Min	Тур	Max	Min	Max	Unit
VIH	High-Level			0.9	V _{CC}			V _{CC}		
	Input Voltage			1.1 to 1.3	0.70 x V _{CC}			0.70 x V _{CC}		
				1.4 to 1.6	0.65 x V _{CC}			0.65 x V _{CC}		
				1.65 to 1.95	0.65 x V _{CC}			0.65 x V _{CC}		
				2.3 to 2.7	1.7			1.7		
				3.0 to 3.6	2.0			2.0		1
VIL	Low-Level			0.9			GND		GND	
	Input Voltage			1.1 to 1.3			0.30 x V _{CC}		0.30 x V _{CC}]
				1.4 to 1.6			0.35 x V _{CC}		0.35 x V _{CC}	v
				1.65 to 1.95			0.35 x V _{CC}		0.35 x V _{CC}]
				2.3 to 2.7			0.7		0.7	1
				3.0 to 3.6			0.8		0.8	
V _{OL}	Low-Level Output Voltage	V _{IN} =	I _{OL} = 20 μA	0.9			0.1		0.1	V
	Oulput voltage	V _{IH} or V _{IL}	l _{OL} = 0.3 mA	1.1 to 1.3			0.25 x V _{CC}		0.25 x V _{CC}	
			l _{OL} = 1.7 mA	1.4 to 1.6			0.25 x V _{CC}		0.25 x V _{CC}	
			I _{OL} = 3.0 mA	1.65 to 1.95			0.45		0.45	1
			I _{OL} = 4.0 mA	2.3 to 2.7			0.4		0.4	1
			I _{OL} = 8.0 mA	3.0 to 3.6			0.4		0.4	1
I _{IN}	Input Leakage Current	0 ≤	V _{IN} ≤ 3.6 V	0 to 3.6			±0.1		±1.0	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} =	V _{CC} or GND	3.6			0.5		10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

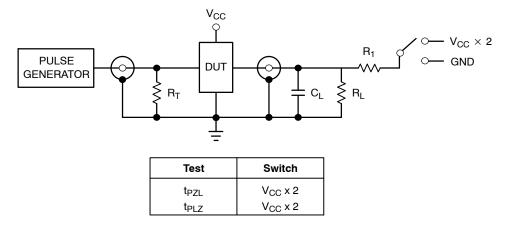
AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$)

					T _A = 25°C	;	T _A −55°C to	= 0 +125°C	
Symbol	Parameter	Test Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Uni
t _{PZL}	Propagation Delay,	C _L = 10 pF,	0.9	-	12	-	-	-	ns
	Enable Time, A to Y	$R_1 = R_L = 5 k\Omega$	1.1 to 1.3	-	5.5	6.8	-	8.8	
	A lo f		1.4 to 1.6	-	4.0	5.7	-	7.3	
			1.65 to 1.95	_	3.3	3.9	-	5.9	
			2.3 to 2.7	-	2.7	3.3	-	4.5	1
			3.0 to 3.6	-	2.4	2.9	-	3.7	
		C _L = 15 pF,	0.9	-	12.5	-	-	-	ns
		$R_1 = R_L = 5 k\Omega$	1.1 to 1.3	-	5.8	7.0	-	9.0	
			1.4 to 1.6	-	4.1	6.0	-	7.4	
			1.65 to 1.95	_	3.4	4.0	-	6.2	
			2.3 to 2.7	_	2.8	3.4	-	4.6	
			3.0 to 3.6	_	2.5	3.0	-	3.7	
		C _L = 30 pF,	0.9	-	13.2	-	-	-	n
		$R_1 = R_L = 5 k\Omega$	1.1 to 1.3	-	6.2	7.4	-	9.4	
			1.4 to 1.6	-	4.5	6.2	-	7.6	
			1.65 to 1.95	-	3.5	4.2	-	6.4	
			2.3 to 2.7	-	3.0	3.6	_	4.7	
			3.0 to 3.6	-	2.6	3.1	-	3.9	
t _{PLZ}	Propagation Delay,	C _L = 10 pF,	0.9	-	8.0	-	-	-	ns
	Disable Time,	$R_1 = R_L = 5 k\Omega$	1.1 to 1.3	-	6.5	10.9	-	11.5	
	A to Y		1.4 to 1.6	-	5.2	7.2	-	8.3	
			1.65 to 1.95	-	4.9	7.0	-	7.8	
			2.3 to 2.7	-	3.8	6.5	-	7.3	
			3.0 to 3.6	-	3.5	6.2	_	6.8	
		C _L = 15 pF,	0.9	_	11.1	-	-	_	n
		$R_1 = R_L = 5 k\Omega$	1.1 to 1.3	-	9.0	13.4	-	14	
			1.4 to 1.6	-	7.9	10	-	10.8	
			1.65 to 1.95	-	7.6	9.5	-	10.5	
			2.3 to 2.7	-	6.3	7.8	-	10	
			3.0 to 3.6	-	6.0	7.2	-	9.3	
		C _L = 30 pF,	0.9	_	16.2	-	-	-	n
		$R_1 = R_L = 5 k\Omega$	1.1 to 1.3	_	14	18.4	-	20	1
			1.4 to 1.6	_	13	15	_	16	
			1.65 to 1.95	_	12.5	14.5	_	15.8	
			2.3 to 2.7	_	11.2	13.5	_	15.4	1
			3.0 to 3.6	_	11	13.2	_	14.3	
C _{IN}	Input Capacitance		0 to 3.6	-	3	-	_	_	p
C _{PD}	Power Dissipation Capacitance (Note 6)		0.9 to 3.6	_	4	-	-	_	pl

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.









ORDERING INFORMATION

Device	Package	Shipping [†]
NL17SG07P5T5G	SOT–953 (Pb–Free)	8000 / Tape & Reel
NL17SG07DFT2G	SC-88A (Pb-Free)	3000 / Tape & Reel
NL17SG07AMUTCG	UDFN6 1.45x1 mm (Pb-Free)	3000 / Tape & Reel
NL17SG07CMUTBG*	UDFN6 1x1 mm (Pb-Free)	3000 / Tape & Reel
NL17SG07MU3TBG*	UDFN6 1x1 mm (Pb-Free)	3000 / Tape & Reel

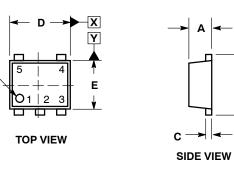
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

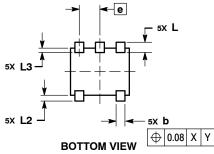
*In Development

PACKAGE DIMENSIONS

SOT-953 CASE 527AE ISSUE E

HE

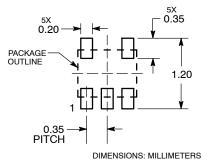




NOTES:
DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
CONTROLLING DIMENSION: MILLIMETERS
MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

I LAO	n, Fhomosions, on d						
	MILLIMETERS						
DIM	MIN	MIN NOM MAX					
Α	0.34	0.37	0.40				
b	0.10	0.15	0.20				
С	0.07	0.12	0.17				
D	0.95	1.00	1.05				
Е	0.75	0.80	0.85				
е		0.35 BS	С				
HE	0.95	1.00	1.05				
L	0.175 REF						
L2	0.05	0.10	0.15				
L3			0.15				

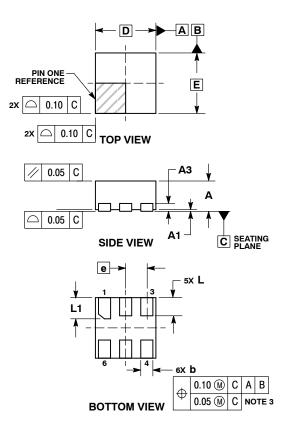
SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6 1.0x1.0, 0.35P CASE 517BX ISSUE O

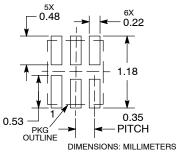


NOTES:

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. 4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIN	IETERS
DIM	MIN	MAX
Α	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.12	0.22
D	1.00	BSC
E	1.00	BSC
е	0.35	BSC
L	0.25	0.35
L1	0.30	0.40

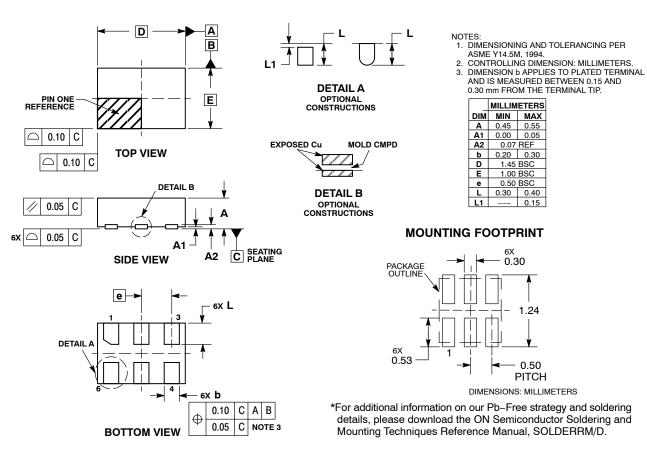
RECOMMENDED SOLDERING FOOTPRINT*



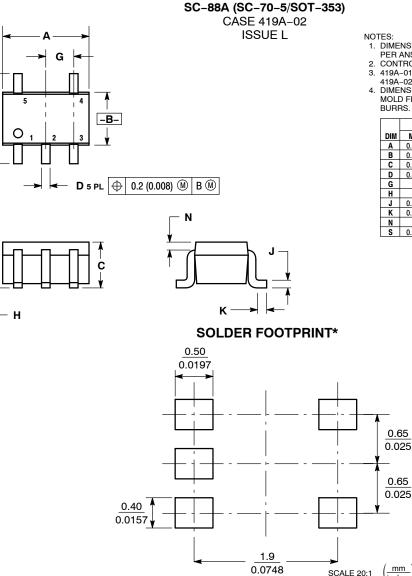
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6 1.45x1.0, 0.5P CASE 517AQ ISSUE O



PACKAGE DIMENSIONS



0.65

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MiniGate is a trademark of Semiconductor Components Industries, LLC (SCILLC)

ON Semiconductor and 💷 are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. Coverage may be accessed at www.onsemi.com/site/pont/atent_Marking.pon. ON semiconductor reserves the right to make changes winnout further notice to any products nerein. ON semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or the rights of others. ON Semiconductor products are not designed intended or suthering of the rupe ner or withing a comparent is literation are any license and any content or a particular designed during or a validated for each customer designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT

S

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

NL17SG07/D

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

- CONTROLLING DIMENSION: INCH. 419A-01 OBSOLETE. NEW STANDARD
- 419A-02. DIMENSIONS A AND B DO NOT INCLUDE

MOLD FLASH, PROTRUSIONS, OR GATE BURBS

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
Κ	0.004	0.012	0.10	0.30
Ν	0.008 REF		0.20	REF
S	0.079	0.087	2.00	2.20